

### General Description

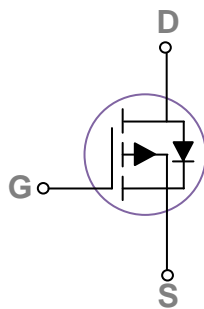
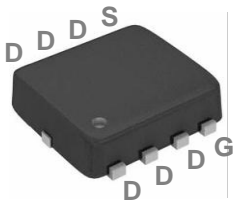
These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	R <sub>DS(ON)</sub>	ID
-30V	23mΩ	-8.5A

### Features

- -30V, -8.5A, R<sub>DS(ON)</sub> = 23mΩ @ V<sub>GS</sub> = -10V
- Fast switching
- Green Device Available
- Suit for -4.5V Gate Drive Applications

### PPAK2x3 Pin Configuration



### Applications

- MB / VGA / Vcore
- POL Applications
- Load Switch
- LED Application

### Absolute Maximum Ratings T<sub>C</sub>=25°C unless otherwise noted

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	-30	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub>	Drain Current – Continuous (T <sub>C</sub> =25°C)	-8.5	A
	Drain Current – Continuous (T <sub>C</sub> =100°C)	-5.3	A
I <sub>DM</sub>	Drain Current – Pulsed <sup>1</sup>	-34	A
P <sub>D</sub>	Power Dissipation (T <sub>C</sub> =25°C)	3	W
	Power Dissipation – Derate above 25°C	0.025	W/°C
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction to ambient	---	90	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction to Case	---	40	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-30	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	$BV_{DSS}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=-1\text{mA}$	---	-0.03	---	$V/^\circ\text{C}$
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=-30V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	-1	$\mu A$
		$V_{DS}=-24V, V_{GS}=0V, T_J=125^\circ\text{C}$	---	---	-10	$\mu A$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 20$	$\mu A$

**On Characteristics**

$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=-10V, I_D=-5A$	---	19	23	$m\Omega$
		$V_{GS}=-4.5V, I_D=-3A$	---	28	34	$m\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=-250\mu A$	-1.2	-1.6	-2.5	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	4	---	$mV/^\circ\text{C}$
$g_{fs}$	Forward Transconductance	$V_{DS}=-10V, I_D=-3A$	---	6.8	---	S

**Dynamic and switching Characteristics**

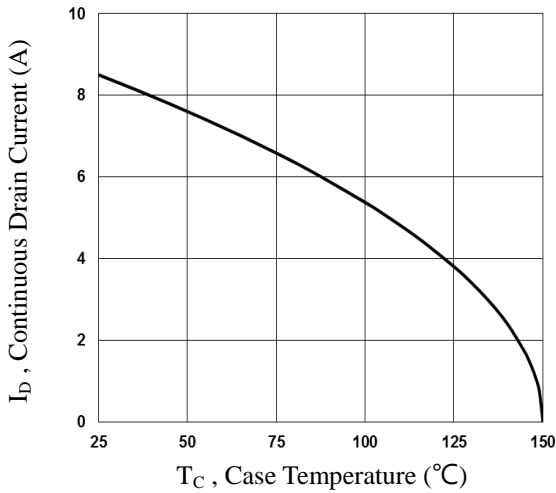
$Q_g$	Total Gate Charge <sup>2,3</sup>	$V_{DS}=-15V, V_{GS}=-4.5V, I_D=-5A$	---	11	17	nC
$Q_{gs}$	Gate-Source Charge <sup>2,3</sup>		---	3.4	6	
$Q_{gd}$	Gate-Drain Charge <sup>2,3</sup>		---	4.2	8	
$T_{d(on)}$	Turn-On Delay Time <sup>2,3</sup>	$V_{DD}=-15V, V_{GS}=-10V, R_G=6\Omega$ $I_D=-1A$	---	5.8	11	ns
$T_r$	Rise Time <sup>2,3</sup>		---	18.8	36	
$T_{d(off)}$	Turn-Off Delay Time <sup>2,3</sup>		---	46.9	90	
$T_f$	Fall Time <sup>2,3</sup>		---	12.3	23	
$C_{iss}$	Input Capacitance	$V_{DS}=-15V, V_{GS}=0V, F=1\text{MHz}$	---	1250	2500	pF
$C_{oss}$	Output Capacitance		---	160	320	
$C_{rss}$	Reverse Transfer Capacitance		---	90	180	

**Drain-Source Diode Characteristics and Maximum Ratings**

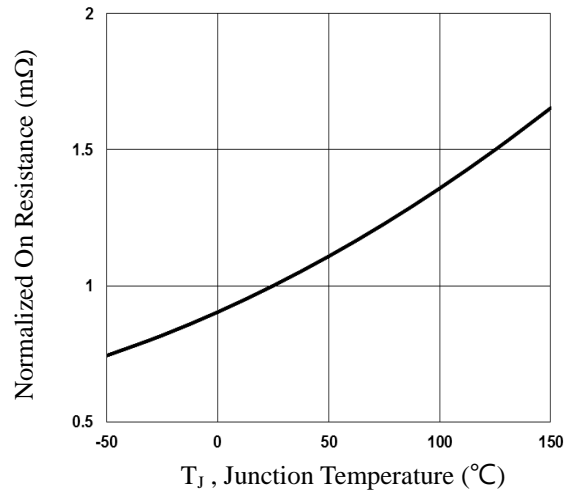
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current	$V_G=V_D=0V$ , Force Current	---	---	-8.5	A
$I_{SM}$	Pulsed Source Current		---	---	-17	A
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0V, I_S=-1A, T_J=25^\circ\text{C}$	---	---	-1	V

Note :

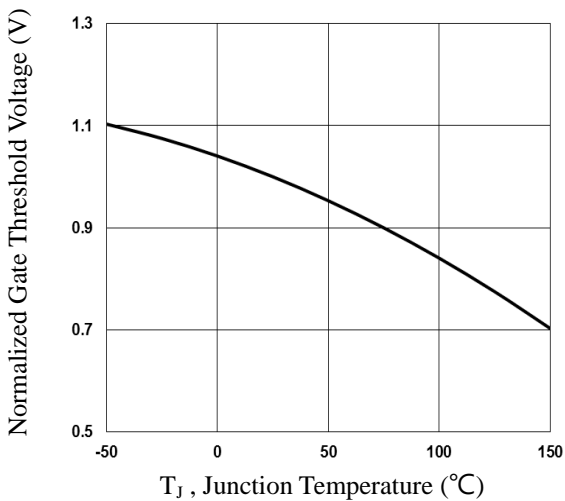
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.



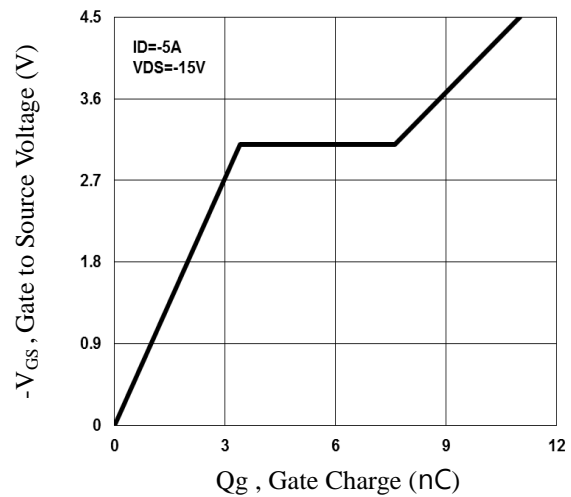
**Fig.1 Continuous Drain Current vs.  $T_c$**



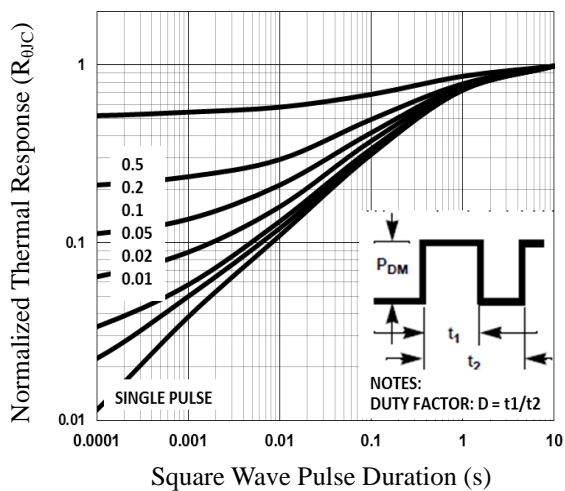
**Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_j$**



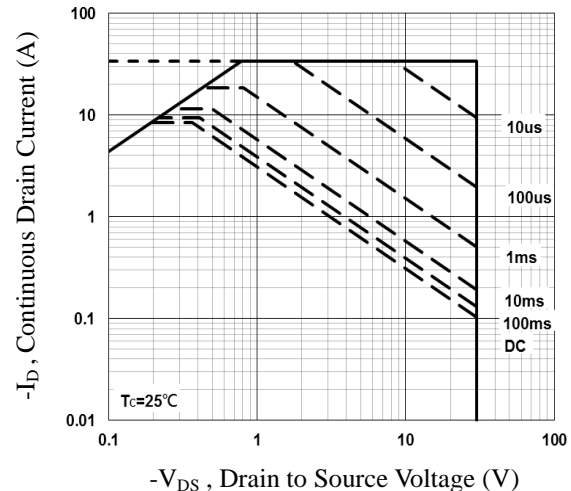
**Fig.3 Normalized  $V_{th}$  vs.  $T_j$**



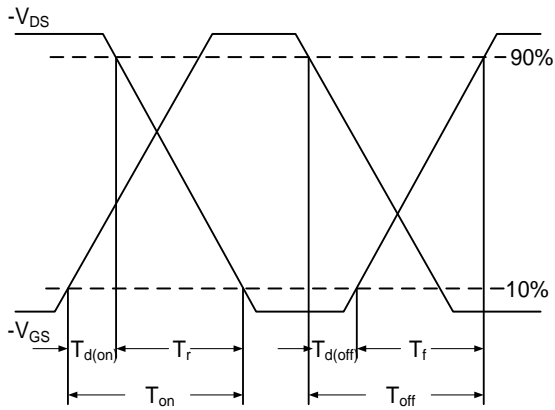
**Fig.4 Gate Charge Waveform**



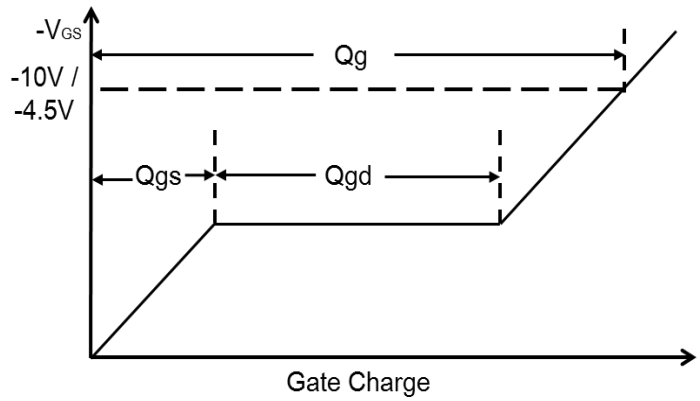
**Fig.5 Normalized Transient Impedance**



**Fig.6 Maximum Safe Operation Area**

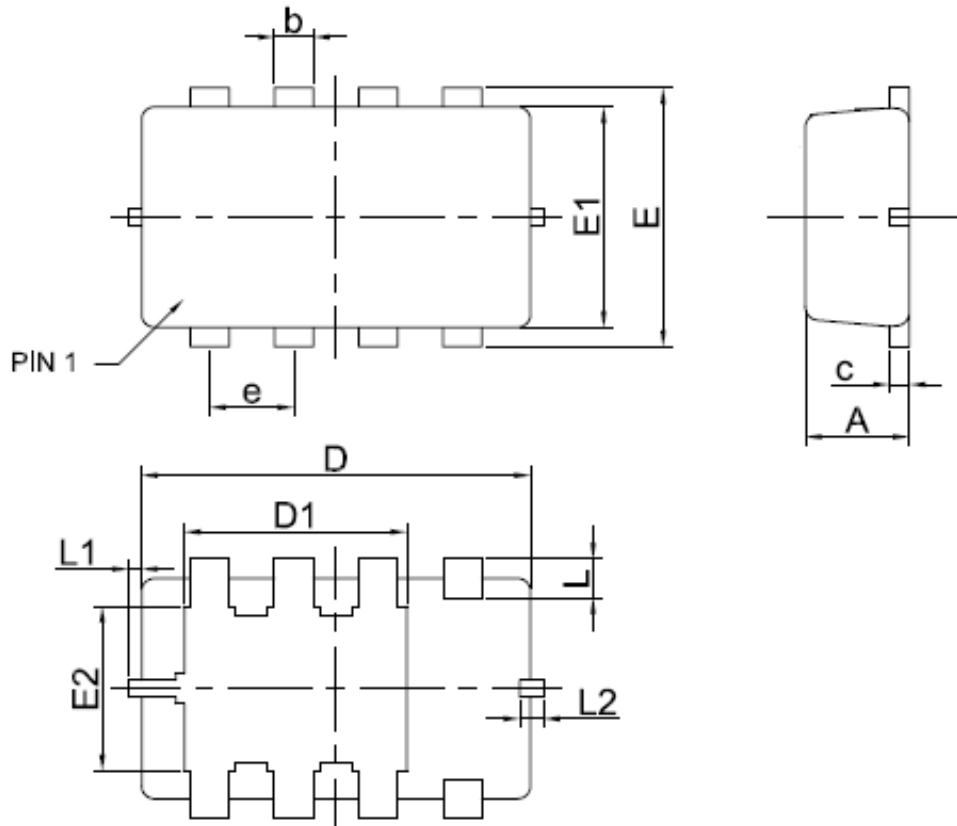


**Fig.7 Switching Time Waveform**



**Fig.8 Gate Charge Waveform**

**PPAK2x3 PACKAGE INFORMATION**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	0.900	0.700	0.035	0.028
b	0.350	0.240	0.014	0.009
c	0.200	0.080	0.008	0.003
D	3.100	2.900	0.122	0.114
D1	1.720	1.520	0.068	0.060
E	2.100	1.900	0.083	0.075
E1	1.800	1.600	0.071	0.063
E2	1.270	1.070	0.050	0.042
e	0.65BSC		0.026BSC	
L	0.400	0.200	0.016	0.008
L1	0.100	0.000	0.004	0.000
L2	0.184	-	0.007	-